HT46R322, (HT46R322 / HT46R342) A/D with OPA Type 8-Bit OTP MCU, Holtek Semiconductor

HT46R342, (HT46R322 / HT46R342) A/D with OPA Type 8-Bit OTP MCU, Holtek Semiconductor



Technical Document

- Tools Information
- FAQs
- Application Note
 - HA0003E Communicating between the HT48 & HT46 Series MCUs and the HT93LC46 EEPROM
- HA0049E Read and Write Control of the HT1380
- HA0051E Li Battery Charger Demo Board Using the HT46R47
- HA0052E Microcontroller Application Battery Charger
- HA0083E Li Battery Charger Demo Board Using the HT46R46

Features

- Operating voltage: f_{SYS}=4MHz: 2.2V~5.5V f_{SYS}=8MHz: 3.3V~5.5V
- 36 bidirectional I/O lines (max.), including 16 LED driver with twice sink/source current
- Single interrupt input shared with an I/O line
- 8-bit programmable timer/event counter with overflow interrupt and 7-stage prescaler
- Integrated crystal and RC oscillator
- Watchdog Timer
- 2048×14 Program Memory capacity HT46R322 4096×15 Program Memory capacity - HT46R342
- 88×8 Data Memory capacity HT46R322

- Up to $0.5 \mu s$ instruction cycle with 8MHz system clock at $V_{DD}{=}5V$
- 6-level subroutine nesting
- 4 channel 12-bit resolution A/D converter
- Integrated single operational amplifier or comparator selectable via configuration option
- Dual 8-bit PWM outputs shared with I/O lines
- Bit manipulation instruction
- Full table read instruction
- 63 powerful instructions
- All instructions executed in one or two machine cycles
- Low voltage reset function

192×8 Data Memory capacity HT46R342
 Integrated PFD function for sound generation
 Power-down and wake-up functions reduce power consumption

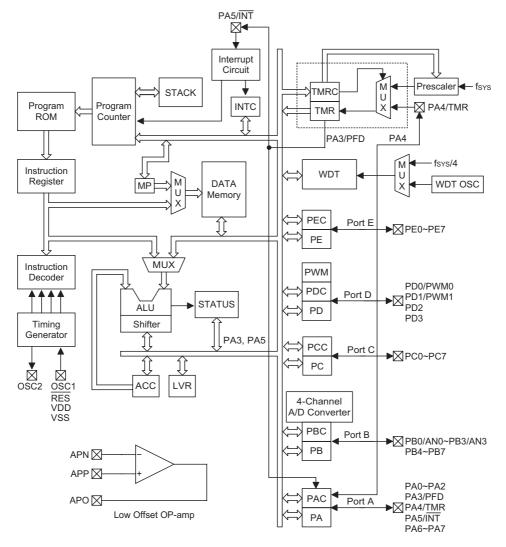
General Description

The HT46R322 and HT46R342 are 8-bit, high performance, RISC architecture microcontroller devices. With their fully integrated A/D converter they are especially suitable for applications which interface to analog signals, such as those from sensors. The addition of an internal operational amplifier/comparator and PWM modulation functions further adds to the analog capability of these devices. With the comprehensive features of low power consumption, I/O flexibility, programmable frequency divider, timer functions, oscillator options, multi-channel A/D Converter OP/Comparator, Pulse Width Modulation function, Power-down and wake-up functions etc, the application scope of these devices is broad and encompasses areas such as sensor signal processing, motor driving, industrial control, consumer products, subsystem controllers, etc.

The HT46R342 is under development and will be available soon.

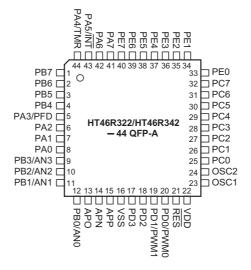


Block Diagram





Pin Assignment



Pin Description

Pin Name	I/O	Options	Description
PA0~PA2 PA3/PFD PA4/TMR PA5/INT PA6, PA7	I/O	Pull-high Wake-up PA3 or PFD	Bidirectional 8-bit input/output port. Each pin can be configured as wake-up input by configuration options. Software instructions determine if the pin is a CMOS output or Schmitt trigger input. Configuration options determine which pins on the port have pull-high resistors. The PFD, TMR and INT pins are pin-shared with PA3, PA4 and PA5, respectively.
PB0/AN0 PB1/AN1 PB2/AN2 PB3/AN3 PB4~PB7	I/O	Pull-high	Bidirectional 8-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt trigger input. Configuration options determine which pins on the port have pull-high resistors. Pins PB0~PB3 are pin-shared with the A/D input pins. The A/D inputs are selected via software instructions. Once selected as an A/D input, the I/O function and pull-high resistor are disabled automatically.
PC0~PC7	I/O	Pull-high	Bidirectional 8-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt trigger input. A configuration option determines if all pins on the port have pull-high resistors.
PD0/PWM0 PD1/PWM1 PD2 PD3	I/O	Pull-high PD0 or PWM0 PD1 or PWM1	Bi-directional 4-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt trigger input. Configuration options determine which pins on this port have pull-high resistors. PD0/PD1 are pin-shared with the PWM0/PWM1 outputs selected via configuration option.
PE0~PE7	I/O	Pull-high	Bidirectional 8-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt trigger input. A configuration option determines if all pins on the port have pull-high resistors.
APO APN APP	0 	_	APO, APN and APP are the internal operational amplifier, output pin, nega- tive input pin and positive input pin respectively .
RES	I	_	Schmitt trigger reset input. Active low.
VDD	_		Positive power supply
VSS			Negative power supply, ground.
OSC1 OSC2	 0	Crystal or RC	OSC1, OSC2 are connected to an external RC network or external crystal, determined by configuration option, for the internal system clock. If the RC system clock option is selected, pin OSC2 can be used to measure the system clock at 1/4 frequency.



Absolute Maximum Ratings

Supply VoltageV_SS-0.3V to V_SS+6.0V	Stora
Input VoltageV_SS-0.3V to V_DD+0.3V	Opera
I _{OL} Total150mA	I _{OH} То
Total Power Dissipation500mW	

Storage Temperature	–50°C to 125°C
Operating Temperature	40°C to 85°C
I _{OH} Total	–100mA

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Characteristics

Operating Temperature: 40°C~+85°C, Ta=25°C

0	P		Test Conditions		T	M	11
Symbol	Parameter	V_{DD}	Conditions	Min.	Тур.	Max.	Unit
V	Operating Voltage		f _{SYS} =4MHz	2.2		5.5	V
V _{DD}	Operating Voltage		f _{SYS} =8MHz	3.3		5.5	V
1	Operating Current	3V	No load, f _{SYS} =4MHz	_	0.6	1.5	mA
I _{DD1}	(Crystal OSC)	5V	ADC disable	_	2	4	mA
I == -	Operating Current	3V	No load, f _{SYS} =4MHz		0.8	1.5	mA
I _{DD2}	(RC OSC)	5V	ADC disable	_	2.5	4	mA
I _{DD3}	Operating Current (Crystal OSC, RC OSC)	5V	No load, f _{SYS} =8MHz ADC disable	_	4	8	mA
	Standby Current	3V	No load,	_	_	5	μA
I _{STB1}	(WDT Enabled)	5V	system HALT	_	_	10	μA
1	Standby Current	3V	No load,	_	_	1	μA
I _{STB2}	(WDT Disabled)	5V	system HALT	_		2	μA
V _{IL1}	Input Low Voltage for I/O Ports, TMR and INT	_		0	_	0.3V _{DD}	V
V _{IH1}	Input High Voltage for I/O Ports, TMR and INT	_	_	0.7V _{DD}	_	V _{DD}	V
V _{IL2}	Input Low Voltage (RES)			0	_	$0.4V_{DD}$	V
V _{IH2}	Input High Voltage (RES)			0.9V _{DD}	_	V _{DD}	V
V _{LVR}	Low Voltage Reset	_		2.7	3.0	3.3	V
	I/O Port Sink Current	3V	V _{OL} =0.1V _{DD}	4	8	_	mA
I _{OL1}	(PA, PD, PE)	5V	V _{OL} =0.1V _{DD}	10	20	_	mA
1	I/O Port Source Current	3V	V _{OH} =0.9V _{DD}	-2	-4	_	mA
I _{OH1}	(PA, PC, PD)	5V	V _{OH} =0.9V _{DD}	-5	-10	_	mA
I	PC Ports Sink Current for LED	3V	V _{OL} =0.1V _{DD}	8	16	_	mA
I _{OL2}	Driver	5V	V _{OL} =0.1V _{DD}	20	40		mA
loue	PE Ports Source Current for LED	3V	V _{OH} =0.9V _{DD}	-4	-8		mA
I _{OH2}	Driver	5V	V _{OH} =0.9V _{DD}	-10	-20	_	mA
R _{PH}	Pull high Posistones	3V	—	20	60	100	kΩ
' PH	Pull-high Resistance	5V		10	30	50	kΩ
V _{AD}	A/D Input Voltage			0		V _{DD}	V



Cumhal	Damanatan		Test Conditions	Min	T	Mari	11
Symbol	Parameter	V _{DD}	Conditions	Min.	Тур.	Max.	Unit
	Additional Power Consumption	3V		_	0.5	1	mA
IADC	if A/D Converter is Used	5V		_	1.5	3	mA
DNL	ADC Differential Non-Linearity	5V	t _{AD} =1μs	_		±2	mA
INL	ADC Integral Non-Linearity	5V	t _{AD} =1μs	_	±2.5	4	mA
RESOLU	Resolution				_	12	Bits

A.C. Characteristics

Ta=25°C

Course had	Parameter		Test Conditions	Min.	T	Max.	Unit
Symbol	Parameter	V _{DD}	Conditions	win.	Тур.	wax.	Unit
£	System Clock	_	2.2V~5.5V	400	_	4000	kHz
f _{SYS}	(Crystal OSC, RC OSC)	_	3.3V~5.5V	400	_	8000	kHz
f	Timer I/P Frequency		2.2V~5.5V	0	_	4000	kHz
f _{TIMER}	(TMR)		3.3V~5.5V	0	_	8000	kHz
+	Wetch dog Oppillator Dagind	3V	_	45	90	180	μs
t _{WDTOSC}	Watchdog Oscillator Period	5V		32	65	130	μs
t _{WDT1}	Watchdog Time-out Period (WDT OSC)			2 ¹⁵		2 ¹⁶	t _{WDTOSC}
t _{WDT2}	Watchdog Time-out Period (System Clock)			2 ¹⁷		2 ¹⁸	t _{SYS}
t _{RES}	External Reset Low Pulse Width	_		1			μs
t _{SST}	System Start-up Timer Period	_	Wake-up from HALT	_	1024		*t _{SYS}
t _{LVR}	Low Voltage Width to Reset	_		0.25	1	2	ms
t _{INT}	Interrupt Pulse Width	_		1		_	μs
t _{AD}	A/D Clock Period		_	1			μs
t _{ADC}	A/D Conversion Time			_	80		t _{AD}
t _{ADCS}	A/D Sampling Time			_	32		t _{AD}

Note: *t_{SYS}=1/f_{SYS}



Ta=25°C

OP Amplifier Electrical Characteristics

<u> </u>	Demonster		Test Conditions		-		
Symbol	Parameter	V _{DD}	Conditions	Min.	Тур.	Max.	Unit
D.C. Elec	trical Characteristic						
V _{DD}	Operating Voltage	_		3	_	5.5	V
V _{OPOS1}	Input Offset Voltage	5V		-10	_	10	mV
V _{OPOS2}	Input Offset Voltage	5V	By Calibration	-2	_	2	mV
V _{CM}	Common Mode Voltage Range	_	_	V _{SS}	_	V _{DD} - 1.4V	V
PSRR	Power Supply Rejection Ratio	_		60	80	_	dB
CMRR	Common Mode Rejection Ratio	5V	V _{CM} =0~V _{DD} -1.4V	60	80	_	dB
t _{RES}	Response Time (Comparator)		Input overdrive=±10mV	_	_	2	μs
A.C. Elec	trical Characteristic				1		
V _{OPOS1}	Open Loop Gain			60	80	_	dB
SR	Slew Rate +, Slew Rate -		No load	_	0.1	_	V/μs
GBW	Gain Band Width	_	R _L =1M, C _L =100p	_	_	100	kHz



Functional Description

Execution Flow

The system clock for the microcontroller is derived from either a crystal or an RC oscillator. The system clock is internally divided into four non-overlapping clocks. One instruction cycle consists of four system clock cycles.

Instruction fetching and execution are pipelined in such a way that a fetch takes an instruction cycle while decoding and execution takes the next instruction cycle. However, the pipelining scheme causes each instruction to effectively execute in a cycle. If an instruction changes the program counter, two cycles are required to complete the instruction.

Program Counter – PC

The program counter controls the sequence in which the instructions stored in program memory are executed and whose contents specify full range of program memory.

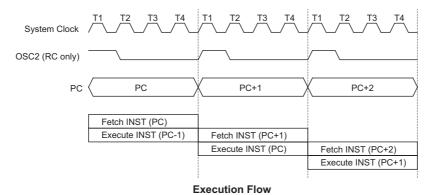
After accessing a program memory word to fetch an instruction code, the contents of the program counter are incremented by one. The program counter then points to the memory word containing the next instruction code.

When executing a jump instruction, conditional skip execution, loading PCL register, subroutine call, initial reset, internal interrupt, external interrupt or return from subroutine, the PC manipulates the program transfer by loading the address corresponding to each instruction.

The conditional skip is activated by instructions. Once the condition is met, the next instruction, fetched during the current instruction execution, is discarded and a dummy cycle replaces it to get the proper instruction. Otherwise proceed with the next instruction.

The lower byte of the program counter, PCL, is a readable and writeable register. Moving data into the PCL performs a short jump. The destination will be within 256 locations.

When a control transfer takes place, an additional dummy cycle is required.



Mode					Pr	ogram	Coun	ter				
wode	*11	*10	*9	*8	*7	*6	*5	*4	*3	*2	*1	*0
Initial Reset	0	0	0	0	0	0	0	0	0	0	0	0
External Interrupt	0	0	0	0	0	0	0	0	0	1	0	0
Timer/Event Counter Overflow	0	0	0	0	0	0	0	0	1	0	0	0
A/D Converter Interrupt	0	0	0	0	0	0	0	0	1	1	0	0
Skip					Pro	gram (Counte	r+2				
Loading PCL	*11	*10	*9	*8	@7	@6	@5	@4	@3	@2	@1	@0
Jump, Call Branch	#11	#10	#9	#8	#7	#6	#5	#4	#3	#2	#1	#0
Return from Subroutine	S11	S10	S9	S8	S7	S6	S5	S4	S3	S2	S1	S0

Program Counter

 Note:
 PC11~PC8: Current Program Counter bits
 \$11~\$0: Stack register bits

 #11~#0: Instruction Code bits
 @7~@0: PCL bits

 For the HT46R322 device the Program Counter is 11 bits wide, i.e. from b10~b0, therefore the b11 column in the table is not applicable.



Program Memory – ROM

The program memory is used to store the program instructions which are to be executed as well as table data and interrupt entries. It is structured into $2K \times 14$ bits for the HT46R322 device and $4K \times 15$ bits for the HT46R342 device, which can be addressed by both the program counter and table pointer.

Certain locations in the program memory are reserved for use by the reset and by the interrupt vectors.

Location 000H

This vector is reserved for program initialisation. After a device reset is initiated, the program will jump to this location and begin execution.

• Location 004H

This vector is used by the external interrupt $\overline{\text{INT}}$. If the external interrupt pin on the device receives a low going edge, the program will jump to this location and begin execution if the external interrupt is enabled and the stack is not full.

Location 008H

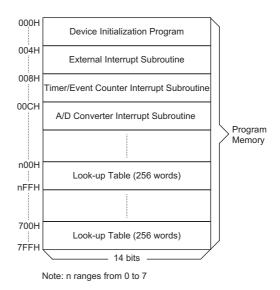
This vector is used by the Timer/Event Counter. If a timer overflow occurs, the program will jump to this location and begin execution if the timer interrupt is enabled and the stack is not full.

Location 00CH

This vector is used by the A/D converter. When an A/D cycle conversion is complete, the program will jump to this location and begin execution if the A/D interrupt is enabled and the stack is not full.

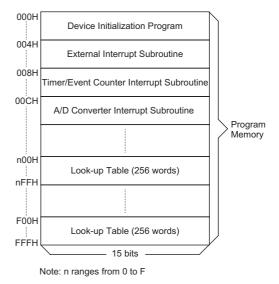
Table location

Any location in the Program Memory space can be used as a look-up table. The instructions "TABRDC [m]" (the current page, 1 page=256 words) and "TABRDL [m]" (the last page) transfer the contents of the lower-order byte to the specified data memory, and the higher-order byte to TBLH. Only the destination of the lower-order byte in the table is well-defined, the other bits of the table word are transferred to the lower portion of TBLH, and the remaining bits are read as "0". The Table Higher-order byte register (TBLH) is read only. The table pointer (TBLP) is a read/write register, which indicates the table location. Before accessing the table, the location must be placed in TBLP. The TBLH register is read only and cannot be



HT46R322/HT46R342

Program Memory – HT46R322



Program Memory – HT46R342

restored. If the main routine and the ISR, Interrupt Service Routine, both employ the table read instruction, the contents of the TBLH in the main routine are likely to be changed by the table read instruction used

		Table Location										
Instruction	*11	*10	*9	*8	*7	*6	*5	*4	*3	*2	*1	*0
TABRDC [m]	P11	P10	P9	P8	@7	@6	@5	@4	@3	@2	@1	@0
TABRDL [m]	1	1	1	1	@7	@6	@5	@4	@3	@2	@1	@0

Table Location

Note: *11~*0: Table location bits

P11~P8: Current program counter bits

@7~@0: Table pointer bits

For the HT46R322 device the Table address is 11 bits wide, i.e. from b10~b0, therefore the b11 column in the table is not applicable.

in the ISR. In such a case errors can occur. Therefore, using the table read instruction in the main routine and the ISR simultaneously should be avoided. However, if the table read instruction has to be used in both the main routine and the ISR, the interrupt is should be disabled prior to the table read instruction. It should not be re-enabled until the TBLH has been backed up. All table related instructions require two cycles to complete their operation. These areas may function as normal program memory depending upon requirements.

Stack Register – STACK

This is a special part of the memory which is used to save the contents of the program counter only. The stack is organized into 6 levels and is neither part of the data nor part of the program space, and is neither readable nor writeable. The activated level is indexed by the stack pointer, known as stack pointer, and is also neither readable nor writeable. At a subroutine call or interrupt acknowledgment, the contents of the program counter are pushed onto the stack. At the end of a subroutine or an interrupt routine, signaled by a return instruction, RET or RETI, the program counter is restored to its previous value from the stack. After a device reset, the stack pointer will point to the top of the stack.

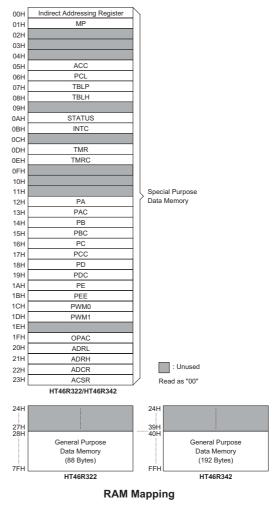
If the stack is full and a non-masked interrupt takes place, the interrupt request flag will be recorded but the acknowledgment will be inhibited. When the stack pointer is decremented, using a RET or RETI instruction, the interrupt will be serviced. This feature prevents a stack overflow allowing the programmer to use the structure more easily. In a similar case, if the stack is full and a "CALL" is subsequently executed, stack overflow occurs and the first entry will be lost. Only the most recent 6 return addresses are stored.

Data Memory - RAM

The data memory has a structure of 115×8 bits for the HT46R322 device and 219×8 bits for the HT46R342 device. The data memory is divided into two functional groups: special function registers and general purpose data memory. The general purpose memory has a structure of 88×8 bits for the HT46R322 device and 192bits×8 bits for the HT46R342 device. Most locations are read/write, but some are read only.

The remaining space between the end of the Special Purpose Data Memory and the beginning of the General Purpose Data Memory is reserved for future expanded usage, reading these locations will obtain a result of "00H". The general purpose data memory, addressed from 28H to 7FH in the HT46R322, and from 40H to FFH in the HT46R342, is used for user data and control information under instruction commands. All of the data memory areas can handle arithmetic, logic, increment, decrement and rotate operations directly. Except for some dedicated bits, each bit in the data memory can

be set and reset by the "SET [m].i" and "CLR [m].i" instructions. They are also indirectly accessible through memory pointer register, MP.



Indirect Addressing Register

Location 00H is an indirect addressing register that is not physically implemented. Any read/write operation on [00H] accesses data memory pointed to by the MP register. Reading location 00H itself indirectly will return the result 00H. Writing indirectly results in no operation.

For the HT46R322 device the memory pointer register, MP, is a 7-bit register, while for the HT46R342 device it is an 8-bit register. For the HT46R322 device, bit 7 of MP is undefined and if read will return the result "1", any write operation will only transfer the lower 7-bits of data to MP.

Accumulator

The accumulator is closely related to ALU operations and can carry out immediate data operations. Any data movement between two data memory locations must pass through the accumulator.



Arithmetic and Logic Unit - ALU

This circuit performs 8-bit arithmetic and logic operations. The ALU provides the following functions:

- Arithmetic operations ADD, ADC, SUB, SBC, DAA
- · Logic operations AND, OR, XOR, CPL
- Rotation RL, RR, RLC, RRC
- Increment and Decrement INC, DEC
- Branch decision SZ, SNZ, SIZ, SDZ

The ALU not only saves the results of a data operation but also changes the status register.

Status Register – STATUS

This 8-bit register contains the zero flag (Z), carry flag (C), auxiliary carry flag (AC), overflow flag (OV), power down flag (PDF), and watchdog time-out flag (TO). It also records the status information and controls the operation sequence.

With the exception of the TO and PDF flags, bits in the status register can be altered by instructions like most other registers. Any data written into the status register will not change the TO or PDF flag. In addition operations related to the status register may give different results from those intended. The TO flag can be affected only by system power-up, a WDT time-out or executing the "CLR WDT" or "HALT" instruction. The PDF flag can be affected only by executing the "HALT" or "CLR WDT" instruction or a system power-up.

The Z, OV, AC and C flags generally reflect the status of the latest operations.

In addition, on entering the interrupt sequence or executing the subroutine call, the status register will not be pushed onto the stack automatically. If the contents of the status are important and if the subroutine can corrupt the status register, precautions must be taken to save it properly.

Interrupt

The devices provide an external interrupt, an internal timer/event counter interrupt and an A/D converter interrupt. The Interrupt Control Register, INTC, contains the interrupt control bits to set the enable or disable and the interrupt request flags.

Bit No.	Label	Function
0	С	C is set if an operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation, otherwise C is cleared. C is also affected by a rotate through carry instruction.
1	AC	AC is set if an operation results in a carry out of the low nibbles in addition or no borrow from the high nibble into the low nibble in subtraction, otherwise AC is cleared.
2	Z	Z is set if the result of an arithmetic or logic operation is zero, otherwise Z is cleared.
3	OV	OV is set if an operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa, otherwise OV is cleared.
4	PDF	PDF is cleared by a system power-up or executing the "CLR WDT" instruction. PDF is set by executing the "HALT" instruction.
5	то	TO is cleared by a system power-up or executing the "CLR WDT" or "HALT" instruction. TO is set by a WDT time-out.
6, 7	_	Unused bit, read as "0"

Status (0AH) Register

Bit No.	Label	Function			
0	EMI	Controls the master (global) interrupt (1=enabled; 0=disabled)			
1	EEI	ntrols the external interrupt (1=enabled; 0=disabled)			
2	ETI	Controls the Timer/Event Counter interrupt (1=enabled; 0=disabled)			
3	EADI	Controls the A/D converter interrupt (1=enabled; 0=disabled)			
4	EIF	External interrupt request flag (1=active; 0=inactive)			
5	TF	Internal Timer/Event Counter request flag (1=active; 0=inactive)			
6	ADF	A/D converter request flag (1=active; 0=inactive)			
7		Unused bit, read as "0"			

INTC (0BH) Register



Once an interrupt subroutine is serviced, all the other interrupts will be blocked by clearing the EMI bit. This scheme may prevent any further interrupt nesting. Other interrupt requests may happen during this interval but only the interrupt request flag is recorded. If a certain interrupt requires servicing within the service routine, the EMI bit and the corresponding bit in INTC may be set to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even if the related interrupt is enabled, until the stack pointer is decremented. If immediate service is desired, the stack must be prevented from becoming full.

All interrupts have a wake-up capability. As an interrupt is serviced, a control transfer occurs by pushing the program counter onto the stack, followed by a branch to a subroutine at a specified location in the program memory. Only the program counter is pushed onto the stack. If the contents of the register or status register are altered by the interrupt service program which corrupts the desired control sequence, the contents should be saved in advance.

External interrupts are triggered by a high to low transition on the $\overline{\rm INT}$ pin, which will set the related interrupt request flag, EIF, which is bit 4 of INTC. When the interrupt is enabled, the stack is not full and the external interrupt is active, a subroutine call to location 04H will occur. The interrupt request flag, EIF, and EMI bits will be cleared to disable other interrupts.

The internal timer/event counter interrupt is initialised by setting the timer/event counter interrupt request flag, TF, which is bit 5 of INTC, caused by a timer overflow. When the interrupt is enabled, the stack is not full and the TF bit is set, a subroutine call to location 08H will occur. The related interrupt request flag, TF, will be reset and the EMI bit cleared to disable further interrupts.

The A/D converter interrupt is initialised by setting the A/D converter request flag, ADF, which is bit 6 of INTC, caused by an end of A/D conversion. When the interrupt is enabled, the stack is not full and the ADF bit is set, a subroutine call to location 0CH will occur. The related interrupt request flag, ADF, will be reset and the EMI bit cleared to disable further interrupts.

During the execution of an interrupt subroutine, other interrupt acknowledgments are held until the RETI instruction is executed or the EMI bit and the related interrupt control bit are set to 1. Of course, the stack must not be full. To return from the interrupt subroutine, a RET or RETI instruction may be executed. A RETI instruction will set the EMI bit to enable an interrupt service, but a RET instruction will not.

Interrupts, occurring in the interval between the rising edges of two consecutive T2 pulses, will be serviced on the latter of the two T2 pulses, if the corresponding interrupts are enabled. In the case of simultaneous requests the following table shows the priority that is applied.

These can be masked by resetting the EMI bit.

Interrupt Source	Priority	Vector
External Interrupt	1	004H
Timer/Event Counter Overflow	2	008H
A/D Converter Interrupt	3	00CH

Once the interrupt request flags, TF, EIF, ADF, are set, they will remain in the INTC register until the interrupts are serviced or cleared by a software instruction.

It is recommended that a program does not use the CALL subroutine within the interrupt subroutine. Interrupts often occur in an unpredictable manner or need to be serviced immediately in some applications. If only one stack is left and enabling the interrupt is not well controlled, the original control sequence will be damaged once the "CALL" operates in the interrupt subroutine.

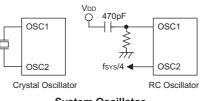
Oscillator Configuration

There are two oscillator circuits in the microcontroller, namely an RC oscillator and a crystal oscillator, the choice of which is determined by a configuration option. When the system enters the Power-down mode the system oscillator stops and ignores external signals to conserve power.

If an RC oscillator is used, an external resistor between OSC1 and VSS is required whose resistance value must range from $24k\Omega$ to $1M\Omega$. The system clock, divided by 4, can be monitored on pin OSC2 if a pull-high resistor is connected. This signal can be used to synchronise external logic. The RC oscillator provides the most cost effective solution, however the frequency of oscillation may vary with VDD, temperature and the process variations. It is, therefore, not suitable for timing sensitive operations where an accurate oscillator frequency is desired.

If the Crystal oscillator is used, a crystal across OSC1 and OSC2 is needed to provide the feedback and phase shift required for the oscillator; no other external components are required. Instead of a crystal, a resonator can also be connected between OSC1 and OSC2 to get a frequency reference, but two external capacitors in OSC1 and OSC2 are required, If the oscillating frequency is less than 1MHz.

The WDT oscillator is a free running on-chip RC oscillator, and requires no external components. Even if the system enters the power down mode, the system clock



System Oscillator



is stopped, but the WDT oscillator keeps running with a period of approximately $65\mu s$ at 5V. The WDT oscillator can be disabled by a configuration option to conserve power.

Watchdog Timer – WDT

The WDT clock source comes from either its own integrated RC oscillator, known as the WDT oscillator, or the instruction clock, which is the system clock divided by 4. The choice of which one is used is decided by a configuration option. This timer is designed to prevent a software malfunction or sequence from jumping to an unknown location with unpredictable results. The Watchdog Timer can be disabled by a configuration option. If the Watchdog Timer is disabled, all the executions related to the WDT result in no operation.

Once the internal WDT oscillator (RC oscillator with a period of $65\mu s$ at 5V nominal) is selected, it is divided by $32768 \sim 65536$ to get a time-out period of approximately 2.1s~4.3s. This time-out period may vary with temperatures, VDD and process variations. If the WDT oscillator is disabled, the WDT clock may still come from the instruction clock and operate in the same manner except that in the Power-down state the WDT may stop counting and lose its protecting purpose. In this situation the logic can only be restarted by external logic.

If the device operates in a noisy environment, using the on-chip RC oscillator (WDT OSC) is strongly recommended, since the HALT instruction will stop the system clock.

The WDT overflow under normal operation will initialise a "chip reset" and set the status bit "TO". But in the Power-down mode, the overflow will initialisze a "warm reset", and only the program counter and SP are reset to zero. To clear the contents of the WDT, three methods are adopted; external reset (a low level on the RES pin), a software instruction and a HALT instruction. The software instruction include "CLR WDT" and the other set – "CLR WDT1" and "CLR WDT2". Of these two types of instruction, only one can be active depending on the configuration option – "CLR WDT times selection option". If the "CLR WDT" is selected (i.e. CLR WDT times equal one), any execution of the "CLR WDT" instruction will clear the WDT. In the case that "CLR WDT1" and "CLR WDT2" are chosen (i.e. CLR WDT times equal two), these two instructions must be executed to clear the WDT; otherwise, the WDT may reset the chip as a result of time-out.

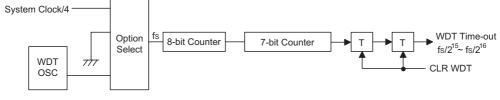
Power Down Operation - HALT

The HALT mode is initialised by the "HALT" instruction and results in the following...

- The system oscillator will be turned off but the WDT oscillator keeps running (if the WDT oscillator is selected).
- The contents of the on chip Data Memory and registers remain unchanged.
- WDT will be cleared and start counting again (if the WDT clock is from the WDT oscillator).
- All of the I/O ports maintain their original status.
- The PDF flag is set and the TO flag is cleared.

The system can leave the HALT mode by means of an external reset, an interrupt, an external falling edge signal on port A or a WDT overflow. An external reset causes a device initialisation and the WDT overflow performs a "warm reset". After the TO and PDF flags are examined, the reason for the chip reset can be determined. The PDF flag is cleared by a system power-up or executing the "CLR WDT" instruction and is set when executing the "HALT" instruction. The TO flag is set if the WDT time-out occurs, and causes a wake-up that only resets the program counter and Stack Pointer; the others keep their original status.

The port A wake-up and interrupt methods can be considered as a continuation of normal execution. Each bit in port A can be independently selected to wake up the device by the options. Awakening from an I/O port stimulus, the program will resume execution of the next instruction. If it is awakening from an interrupt, two sequences may happen. If the related interrupt is dis-







abled or the interrupt is enabled but the stack is full, the program will resume execution at the next instruction. If the interrupt is enabled and the stack is not full, the regular interrupt response takes place. If an interrupt request flag is set to "1" before entering the HALT mode, the wake-up function of the related interrupt will be disabled. Once a wake-up event occurs, it takes 1024 t_{SYS} (system clock period) to resume normal operation. In other words, a dummy period will be inserted after wake-up. If the wake-up results from an interrupt acknowledgment, the actual interrupt subroutine execution will be delayed by one or more cycles. If the wake-up results in the next instruction execution, this will be executed immediately after the dummy period is finished.

To minimise power consumption, all the I/O pins should be carefully managed before entering the status.

Reset

There are three ways in which a reset can occur:

- RES reset during normal operation
- RES reset during HALT
- WDT time-out reset during normal operation

The WDT time-out during HALT is different from other chip reset conditions, since it can perform a "warm reset" that resets only the program counter and stack pointer, leaving the other circuits in their original state. Some registers remain unchanged during other reset conditions. Most registers are reset to the "initial condition" when the reset conditions are met. By examining the PDF and TO flags, the program can distinguish between different "chip resets".

то	PDF	RESET Conditions
0	0	RES reset during power-up
u	u	RES reset during normal operation
0	1	RES wake-up HALT
1	u	WDT time-out during normal operation
1	1	WDT wake-up HALT

Note: "u" means "unchanged"

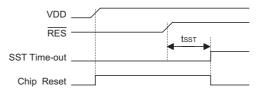
To guarantee that the system oscillator is started and stabilized, the SST (System Start-up Timer) provides an extra-delay of 1024 system clock pulses when the system reset (power-up, WDT time-out or RES reset) or the system awakes from the HALT state.

When a system reset occurs, the SST delay is added during the reset period. Any wake-up from HALT will enable the SST delay.

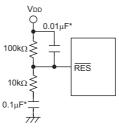
An extra option load time delay is added during system reset (power-up, WDT time-out at normal mode or $\overline{\text{RES}}$ reset).

The functional unit chip reset status are shown below.

Program Counter	000H
Interrupt	Disable
WDT	Clear. After master reset, WDT begins counting
Timer/Event Counter	Off
Input/Output Ports	Input mode
Stack Pointer	Points to the top of the stack

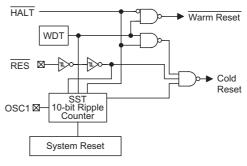


Reset Timing Chart



Reset Circuit

Note: "*" Ensure that the length of the wiring, which is connected to the RES pin is as short as possible, to avoid noise interference.



Reset Configuration



Register	Reset (Power On)	WDT Time-out (Normal Operation)	RES Reset (Normal Operation)	RES Reset (HALT)	WDT Times-out (HALT)*
MP - HT46R322	1xxx xxxx	1սսս սսսս	1นนน นนนน	1uuu uuuu	1นนน นนนน
MP - HT46R342	XXXX XXXX	นนนน นนนน	นนนน นนนน	uuuu uuuu	นนนน นนนน
ACC	XXXX XXXX	นนนน นนนน	นนนน นนนน	นนนน นนนน	นนนน นนนน
PCL	0000 0000	0000 0000	0000 0000	0000 0000	0000 0000
TBLP	XXXX XXXX	นนนน นนนน	นนนน นนนน	นนนน นนนน	นนนน นนนน
TBLH - HT46R322	xx xxxx	uu uuuu	uu uuuu	uu uuuu	uu uuuu
TBLH - HT46R342	-xxx xxxx	-นนน นนนน	-uuu uuuu	-uuu uuuu	-uuu uuuu
STATUS	00 xxxx	1u uuuu	uu uuuu	01 uuuu	11 uuuu
INTC	-000 0000	-000 0000	-000 0000	-000 0000	-uuu uuuu
TMR	XXXX XXXX	XXXX XXXX	xxxx xxxx	xxxx xxxx	นนนน นนนน
TMRC	00-0 1000	00-0 1000	00-0 1000	00-0 1000	uu-u uuuu
PA	1111 1111	1111 1111	1111 1111	1111 1111	นนนน นนนน
PAC	1111 1111	1111 1111	1111 1111	1111 1111	นนนน นนนน
РВ	1111 1111	1111 1111	1111 1111	1111 1111	นนนน นนนน
PBC	1111 1111	1111 1111	1111 1111	1111 1111	นนนน นนนน
PC	1111 1111	1111 1111	1111 1111	1111 1111	นนนน นนนน
PCC	1111 1111	1111 1111	1111 1111	1111 1111	นนนน นนนน
PD	1111	1111	1111	1111	uuuu
PDC	1111	1111	1111	1111	uuuu
PE	1111 1111	1111 1111	1111 1111	1111 1111	นนนน นนนน
PEC	1111 1111	1111 1111	1111 1111	1111 1111	นนนน นนนน
PWM0	XXXX XXXX	XXXX XXXX	xxxx xxxx	xxxx xxxx	นนนน นนนน
PWM1	XXXX XXXX	XXXX XXXX	xxxx xxxx	xxxx xxxx	นนนน นนนน
OPAC	0000 1000	0000 1000	0000 1000	0000 1000	นนนน นนนน
ADRL	xxxx	xxxx	xxxx	xxxx	uuuu
ADRH	XXXX XXXX	XXXX XXXX	xxxx xxxx	xxxx xxxx	นนนน นนนน
ADCR	0100 0000	0100 0000	0100 0000	0100 0000	นนนน นนนน
ACSR	100	100	100	100	uuu

The registers' states are summarised in the following table.

Note: "*" stands for warm reset

"u" stands for unchanged

"x" stands for unknown



Timer/Event Counter

A timer/event counter is implemented in the microcontroller. The timer/event counter contains an 8-bit programmable count-up counter whose clock source may come from an external source or from the system clock.

Using an external clock input allows the user to count external events, measure time internals or pulse widths, or generate an accurate time base. While using the internal clock allows the user to generate an accurate time base.

The timer/event counter can generate a PFD signal by using the external or internal clock. The PFD frequency is determined by the equation $f_{INT}/[2\times(256-N)]$.

There are 2 registers related to the timer/event counter; TMR and TMRC. Two physical registers are mapped to the TMR location. Writing to TMR places the start value in the timer/event counter preload register, while reading TMR retrieves the contents of the timer/event counter. The TMRC register is a timer/event counter control register, which defines some options.

The TM0 and TM1 bits define the operating mode. The event count mode is used to count external events, which means the clock source emanates from the external TMR pin. The timer mode functions as a normal timer with the clock source coming from the f_{INT} clock. The pulse width measurement mode can be used to count the high or low level duration of the external signal on TMR. The counting is based on f_{INT} .

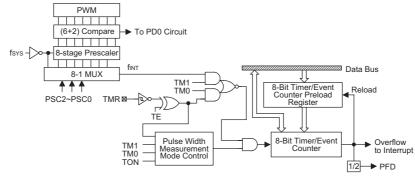
In the event count or timer mode, once the timer/event counter starts counting, it will count from the current contents in the timer/event counter to FFH. Once an overflow occurs, the counter is reloaded from the timer/event counter preload register and generates an interrupt request flag, TF, which is bit 5 of INTC, at the same time.

In the pulse width measurement mode with the TON and TE bits equal to one, once TMR has received a transient from low to high (or high to low if the TE bits is "0") it will start counting until TMR returns to the original level and resets the TON bit. The measured result will remain in the timer/event counter even if the activated transient occurs again. Therefore only a one cycle measurement is made. Not until the TON bit is once again set, will the cycle measurement function again if further transient pulses are received. Note that, in this operating mode, the timer/event counter starts counting not according to the logic level but according to the transient edges. In the case of counter overflows, the counter is reloaded from the timer/event counter preload register and issues the interrupt request just like the other two modes. To enable the counting operation, the timer ON bit, TON, which is bit 4 of TMRC, should be set to 1. In the pulse width measurement mode, the TON bit will be cleared automatically after the measurement cycle is completed. But in the other two modes the TON bit can only be reset by instructions. The overflow of the timer/event counter is one of the wake-up sources. No matter what the operation mode is, writing a 0 to ETI can disable the interrupt service.

Bit No.	Label	Function
0 1 2	PSC0 PSC1 PSC2	Defines the prescaler stages, PSC2, PSC1, PSC0= $000: f_{INT}=f_{SYS}$ $001: f_{INT}=f_{SYS}/2$ $010: f_{INT}=f_{SYS}/4$ $011: f_{INT}=f_{SYS}/8$ $100: f_{INT}=f_{SYS}/16$ $101: f_{INT}=f_{SYS}/32$ $110: f_{INT}=f_{SYS}/64$ $111: f_{INT}=f_{SYS}/128$
3	TE	Defines the TMR active edge of the timer/event counter: In Event Counter Mode (TM1,TM0)=(0,1): 1:count on falling edge; 0:count on rising edge In Pulse Width measurement mode (TM1,TM0)=(1,1): 1: start counting on the rising edge, stop on the falling edge; 0: start counting on the falling edge, stop on the rising edge
4	TON	Enable or disable the timer counting (0=disable; 1=enable)
5	—	Unused bits, read as "0"
6 7	TM0 TM1	Defines the operating mode (TM1, TM0)= 01=Event count mode (external clock) 10=Timer mode (internal clock) 11=Pulse width measurement mode 00=Unused

TMRC (0EH) Register





Timer/Event Counter

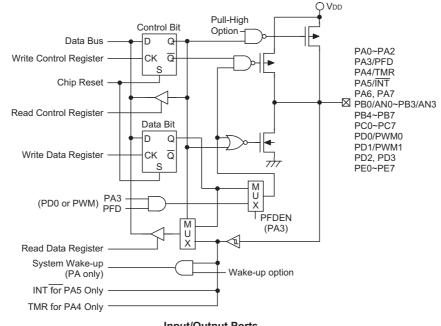
In the case of a timer/event counter OFF condition, writing data to the timer/event counter preload register will also reload that data to the timer/event counter. But if the timer/event counter is turned on, data written to it will only be kept in the timer/event counter preload register. The timer/event counter will still operate until an overflow occurs. When the timer/event counter is read, the clock will be blocked to avoid errors. As clock blocking may results in a counting error, this must be taken into consideration by the programmer.

Bit0~bit2 of the TMRC register can be used to define the pre-scaling stages of the internal clock sources of the timer/event counter. The definitions are as shown. The overflow signal of timer/event counter can be used to generate the PFD signal.

Input/Output Ports

There are 19 bidirectional input/output lines in the microcontroller, labeled as PA, PB, PC, PD and PE, which are mapped to the data memory of [12H], [14H], [16H], [18H] and [1AH] respectively. All of these I/O ports can be used for input and output operations. For input operation, these ports are non-latching, that is, the inputs must be ready at the T2 rising edge of instruction "MOV A,[m]" (m=12H, 14H, 16H, 18H or 1AH). For output operation, all the data is latched and remains unchanged until the output latch is rewritten.

Each I/O line has its own control register (PAC, PBC, PCC, PDC, PEC) to control the input/output configuration. With this control register, CMOS output or Schmitt trigger input with or without pull-high resistor structures can be reconfigured dynamically (i.e. on-the-fly) under software control. To function as an input, the corresponding latch of the control register must write "1". The input source also depends on the control register. If the control register bit is "1", the input will read the pad state. If the control register bit is "0", the contents of the latches will move to the internal bus. The latter is possible in the "read-modify-write" instruction.



Input/Output Ports



After a device reset, the input/output lines will default to inputs and remain at a high level or floating state, dependent upon the pull-high configuration options. Each bit of these input/output latches can be set or cleared by the "SET [m].i" and "CLR [m].i" (m=12H, 14H, 16H, 18H or 1AH) instructions.

Some instructions first input data and then follow the output operations. For example, "SET [m].i", "CLR [m].i", "CPL [m]", "CPLA [m]" read the entire port states into the CPU, execute the defined operations (bit-operation), and then write the results back to the latches or the accumulator.

Each line of port A has the capability of waking-up the device.

Each I/O line has a pull-high option. Once the pull-high configuration option is selected, the I/O line has a pull-high resistor, otherwise, there's none. Take note that a non-pull-high I/O line operating in input mode will cause a floating state.

Pin PA3 is pin-shared with the PFD signal. If the PFD configuration option is selected, the output signal in the output mode for PA3 will be the PFD signal generated by the timer/event counter overflow signal. The input mode always retains its original functions. Once the PFD option is selected, the PFD output signal is controlled by the PA3 data register only. Writing a "1" to the PA3 data register will enable the PFD output function and writing "0" will force the PA3 to remain at "0". The I/O functions for PA3 are shown below.

I/O	l/P	O/P	l/P	O/P
Mode	(Normal)	(Normal)	(PFD)	(PFD)
PA3	Logical	Logical	Logical	PFD
	Input	Output	Input	(Timer on)

Note: The PFD frequency is the timer/event counter overflow frequency divided by 2.

Pins PA5 and PA4 are pin-shared with $\overline{\text{INT}}$ and TMR pins respectively.

The PB can also be used as A/D converter inputs. The A/D function will be described later. There are two PWM functions shared with pins PD0 and PD1. If the PWM functions are enabled, the PWM signals will appear on PD0 and PD1, the pins are setup as outputs. Writing a "1" to the PD0 or PD1 data register will enable the PWM outputs to function while writing a "0" will force the PD0 and PD1 outputs to remain at "0". The I/O functions of PD0 and PD1 are as shown.

I/O	l/P	O/P	l/P	O/P
Mode	(Normal)	(Normal)	(PWM)	(PWM)
PD0	Logical	Logical	Logical	PWM0
PD1	Input	Output	Input	PWM1

It is recommended that unused I/O lines should be setup as output pins by software instructions to avoid consuming power under input floating states.

PWM

The microcontroller provides a 2 channel (6+2) bits PWM0/PWM1 output shared with PD0/PD1. The PWM channel has its data register denoted as PWM0 and PWM1. The frequency source of the PWM counter comes from f_{SYS} . The PWM register is an eight bit register. Once PD0/PD1 are selected as PWM outputs and the output function of PD0/PD1 is enabled (PDC.0="0" or PDC.1="0"), writing a 1 to the PD0/PD1 data register will enable the PWM output function while writing a "0" will force the PD0/PD1 outputs to stay at "0".

A PWM cycle is divided into four modulation cycles (modulation cycle 0~modulation cycle 3). Each modulation cycle has 64 PWM input clock period. In a (6+2) bit PWM function, the contents of the PWM register is divided into two groups. Group 1 of the PWM register is denoted by DC which is the value of PWM.7~PWM.2.

Group 2 is denoted by AC which is the value of $PWM.1 \sim PWM.0$.

In a PWM cycle, the duty cycle of each modulation cycle is shown in the table.

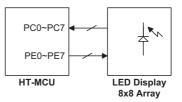
Parameter	AC (0~3)	Duty Cycle
Modulation cycle i	i <ac< td=""><td>DC+1 64</td></ac<>	DC+1 64
(i=0~3)	i≥AC	DC 64

The modulation frequency, cycle frequency and cycle duty of the PWM output signal are summarized in the following table.

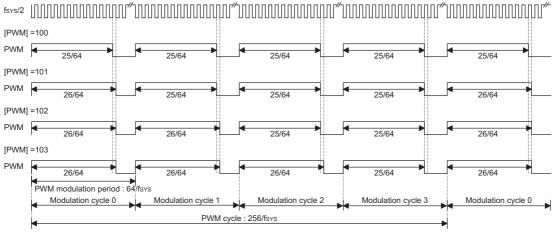
PWM Modulation Frequency	PWM Cycle Frequency	PWM Cycle Duty	
f _{SYS} /64	f _{SYS} /256	[PWM]/256	

LED Driver

The device provides a maximum of 8×8 LED drivers which uses I/O Ports PC and PE with double the usual sink/source current drive capabilities. To use the LED driver function, PC and PE must be setup as outputs.









A/D Converter

A 4 channel 12-bit resolution A/D converter is implemented in the microcontrollers. The reference voltage for the A/D is VDD. The A/D converter contains 4 special registers, which are; ADRL, ADRH, ADCR and ACSR. The ADRH and ADRL registers are the A/D conversion result register higher-order byte and lower-order byte and are read-only. After the A/D conversion has completed, the ADRL and ADRH registers should be read to get the conversion result data. The ADCR register is an A/D converter control register, which defines the A/D channel number, analog channel select, start A/D conversion control bit and the end of A/D conversion flag. It is used to start an A/D conversion, define the PB configuration, select the converted analog channel, and give the START bit a raising edge and a falling edge $(0\rightarrow 1\rightarrow 0)$. At the end of an A/D conversion, the EOCB bit is cleared and an A/D converter interrupt occurs, if the A/D converter interrupt is enabled. The ACSR register is an A/D clock setting register, which is used to select the A/D clock source.

The A/D converter control register is used to control the A/D converter. Bit2~bit0 of the ADCR regsiter are used to select an analog input channel. There are a total of four channels to select. Bit5~bit3 of the ADCR register are used to set the PB configurations. PB can be configured as an analog input or as a digital I/O line decided by these 3 bits. Once a PB line is selected as an analog input, the I/O functions and pull-high resistor of this I/O line are disabled, and the A/D converter circuit is powered on. The EOCB bit, bit6 of ADCR, is the end of A/D conversion flag. This bit is monitored to check when the A/D conversion has completed. The START bit of the ADCR register is used to initiate the A/D conversion

process. When the START bit is provided with a raising edge and then a falling edge, the A/D conversion process will begin. In order to ensure that the A/D conversion is completed, the START should remain at "0" until the EOCB flag is cleared to "0" which indicates the end of the A/D conversion.

Bit 7 of the ACSR register is used for test purposes only and must not be used for other purposes by the application program. Bit1 and bit0 of the ACSR register are used to select the A/D clock source.

When the A/D conversion has completed, the A/D interrupt request flag will be set. The EOCB bit is set to "1" when the START bit is set from "0" to "1".

Important Note for A/D initialisation:

Special care must be taken to initialise the A/D converter each time the Port B A/D channel selection bits are modified, otherwise the EOCB flag may be in an undefined condition. An A/D initialisation is implemented by setting the START bit high and then clearing it to zero within 10 instruction cycles of the Port B channel selection bits being modified. Note that if the Port B channel selection bits are all cleared to zero then an A/D initialisation is not required.

Register	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
ADRL	D3	D2	D1	D0		—		_
ADRH	D11	D10	D9	D8	D7	D6	D5	D4

Note: D0~D11 is A/D conversion result data bit LSB~MSB.

ADRL (20H), ADRH (21H) Register

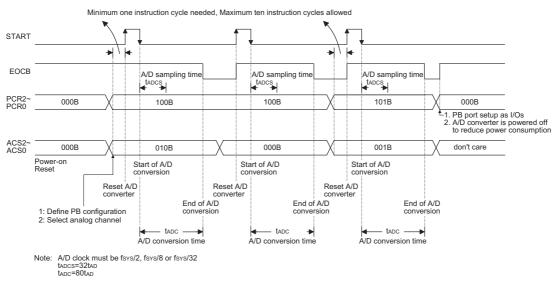


Bit No.	Label	Function
0 1 2	ACS0 ACS1 ACS2	ACS2, ACS1, ACS0: Select A/D channel 0, 0, 0: AN0 0, 0, 1: AN1 0, 1, 0: AN2 0, 1, 1: AN3 1, X, X: undefined, cannot be used
2	_	Unused bit, read as "0".
3 4 5	PCR0 PCR1 PCR2	PCR2, PCR1, PCR0: PB3~PB0 configurations 0, 0, 0: PB3 PB2 PB1 PB0 (The ADC circuit is power off to reduce power consumption.) 0, 0, 1: PB3 PB2 PB1 AN0 0, 1, 0: PB3 PB2 AN1 AN0 0, 1, 1: PB3 AN2 AN1 AN0 1, x, x: AN3 AN2 AN1 AN0
6	EOCB	Indicates end of A/D conversion. (0 = end of A/D conversion) Each time bits 3~5 change state the A/D should be initialised by issuing a START signal, other- wise the EOCB flag may have an undefined condition. See "Important note for A/D initialisation".
7	START	Starts the A/D conversion. $(0\rightarrow 1\rightarrow 0=$ start; $0\rightarrow 1=$ Reset A/D converter and set EOCB to "1")

ADCR (22H) Register

Bit No.	Label	Function
0 1	ADCS0 ADCS1	
2~6	—	Unused bit, read as "0".
7	TEST	For internal test only.

ACSR (23H) Register



A/D Conversion Timing



The following two programming examples illustrate how to setup and implement an A/D conversion. In the first example, the method of polling the EOCB bit in the ADCR register is used to detect when the conversion cycle is complete, whereas in the second example, the A/D interrupt is used to determine when the conversion is complete.

Example: using EOCB Polling Method to detect end of conversion

clr	EADI	; disable ADC interrupt
mov	a,00000001B	
mov	ACSR,a	; setup the ACSR register to select f _{SYS} /8 as the A/D clock
mov	a,00100000B	; setup ADCR register to configure Port PB0~PB3 as A/D inputs
mov	ADCR,a	; and select AN0 to be connected to the A/D converter
	:	
	:	; As the Port B channel bits have changed the following START
		; signal (0-1-0) must be issued within 10 instruction cycles
Start con		
Start_conv clr	START	
set	START	: reset A/D
clr	START	; start A/D
Polling E		
SZ	EOCB	; poll the ADCR register EOCB bit to detect end of A/D conversion
jmp	polling_EOC	; continue polling
mov	a,ADRH	; read conversion result high byte value from the ADRH register
mov	adrh_buffer,a	; save result to user defined memory
mov	a,ADRL	; read conversion result low byte value from the ADRL register
mov	adrl_buffer,a	; save result to user defined memory
	:	
	:	
jmp	start_conversion	; start next A/D conversion
Example:	using interrupt method to	o detect end of conversion
clr	EADI	; disable ADC interrupt
mov	a,0000001B	
mov	ACSR,a	; setup the ACSR register to select f _{SYS} /8 as the A/D clock
	00100000	
mov	a,00100000B	; setup ADCR register to configure Port PB0~PB3 as A/D inputs
mov	ADCR,a	; and select AN0 to be connected to the A/D converter
	•	; As the Port B channel bits have changed the following START
		; signal (0-1-0) must be issued within 10 instruction cycles
	:	
Start conv	version:	
clr	START	
set	START	; reset A/D
clr	START	; start A/D
clr	ADF	; clear ADC interrupt request flag
set	EADI	; enable ADC interrupt
set	EMI	; enable global interrupt
	:	
	:	
	: Trunt convice reviting	
	errupt service routine	
ADC_ISR: mov	acc stack,a	; save ACC to user defined memory
mov	a.STATUS	, save need to door domind momory
mov	status stack,a	; save STATUS to user defined memory
	:	,,
	:	
mov	a,ADRH	; read conversion result high byte value from the ADRH register
mov	adrh_buffer,a	; save result to user defined register
mov	a,ADRL	; read conversion result low byte value from the ADRL register
mov	adrl_buffer,a	; save result to user defined register
clr	START	
set	START	; reset A/D
clr	START	; start A/D
	:	
EXIT INT		
	ISR	
mov mov	a,status_stack	: restore STATUS from user defined memory
mov	a,status_stack STATUS,a	; restore STATUS from user defined memory ; restore ACC from user defined memory
	a,status_stack	; restore STATUS from user defined memory ; restore ACC from user defined memory
mov mov	a,status_stack STATUS,a	



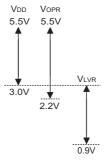
Low Voltage Reset – LVR

The microcontroller provides a low voltage reset circuit in order to monitor the supply voltage of the device. If the supply voltage of the device is within the range 0.9V~V_{LVR}, such as what happens when changing a battery, the LVR will automatically reset the device internally.

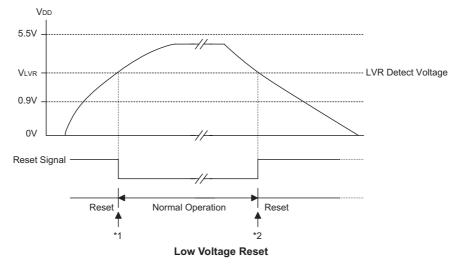
The LVR includes the following specifications:

- The low voltage (0.9V~V_{LVR}) has to remain in its original state to exceed t_{LVR}. If the low voltage state does not exceed t_{LVR}, the LVR will ignore it and will not perform a reset function.
- The LVR uses the "OR" function with the external RES signal to perform a chip reset.





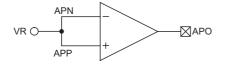
Note: V_{OPR} is the voltage range for proper chip operation at 4MHz system clock.



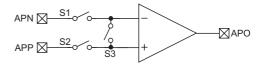
- Note: *1: To make sure that the system oscillator has stabilised, the SST provides an extra delay of 1024 system clock pulses before beginning normal operation.
 - *2: Since the low voltage has to maintain in its original state and exceed t_{LVR} , therefore t_{LVR} delay enter the reset mode.

OP Amplifier/Comparator

The devices include an integrated operational amplifier or comparator, selectable via configuration option. The default is function is comparator. The input voltage offset is adjustable by using a common mode input to calibrate the offset value.



The calibration process is as follows:



- Set bit AOFM=1 to select the offset cancellation mode this closes switch S3
- Set the ARS bit to select which input pin is the reference voltage closes either switch S1 or S2
- Adjust bits AOF0~AOF3 until the output status OPAOP has changed.
- Set AOFM=0 to select the normal operating mode



Bit No.	Label	Function
0	AOF0	
1	AOF1	OD amp/comparator input affect valtage concellation control hits
2	AOF2	OP amp/comparator input offset voltage cancellation control bits
3	AOF3	
4	ARS	OP amp/comparator input offset voltage cancellation reference selection bit 1/0 : select OPP/OPN (CP/CN) as the reference input
5	AOFM	Input offset voltage cancellation mode and OP amp/comparator mode selection 1: input offset voltage cancellation mode 0: OP amp/comparator
6	OPAOP	OP amp/comparator output; positive logic
7	OPAEN	OP amp/comparator enable/disable (1/0) If OP/comparator is disabled, output is floating.

OPAC (1FH) Register

If the OP amp/comparator is disabled, the power consumption will be very small. To ensure that power consumption is minimised when the device is in the Power-down mode, the OP amp/comparator should be switched off by clearing bit OPAEN to 0 before entering the Power-down mode.

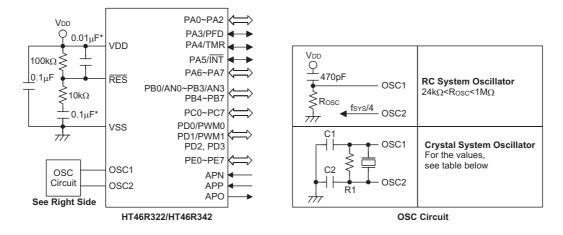
Configuration Options

The following table shows the various microcontroller configuration options. All of the configuration options must be properly defined to ensure correct system functioning.

No.	Options
1	WDT clock source: WDTOSC or T1 (f _{SYS} /4)
2	WDT function: enable or disable
3	CLRWDT instruction(s): one or two clear WDT instruction(s)
4	System oscillator: RC or crystal
5	Pull-high resistors (PA, PB, PD): none or pull-high
6	PWM enable or disable
7	PA0~PA7 wake-up: enable or disable
8	PFD enable or disable
9	Low voltage reset selection: enable or disable LVR function.
10	Comparator or OP selection



Application Circuits



The following table shows the C1, C2 and R1 values corresponding to the different crystal values. (For reference only)

Crustel en Desenaten	HT4	6R322	HT46R342			
Crystal or Resonator	C1, C2	R1	C1, C2	R1		
8MHz Crystal	10pF	4.3kΩ	TBD	TBD		
8MHz Resonator	10pF	4.7kΩ	TBD	TBD		
4MHz Crystal	25pF	12kΩ	TBD	TBD		
4MHz Resonator	10pF	12kΩ	TBD	TBD		
3.58MHz Crystal	25pF	12kΩ	TBD	TBD		
3.58MHz Resonator	10pF	12kΩ	TBD	TBD		
2MHz Crystal & Resonator	30pF	12kΩ	TBD	TBD		
1MHz Crystal	68pF	18kΩ	TBD	TBD		
480kHz Resonator	300pF	10kΩ	TBD	TBD		
455kHz Resonator	300pF	10kΩ	TBD	TBD		
429kHz Resonator	300pF	10kΩ	TBD	TBD		
400kHz Resonator	300pF	10kΩ	TBD	TBD		

The function of the resistor R1 is to ensure that the oscillator will switch off should low voltage conditions occur. Such a low voltage, as mentioned here, is one which is less than the lowest value of the MCU operating voltage. Note however that if the LVR is enabled then R1 can be removed.

Note: The resistance and capacitance for the reset circuit should be designed in such a way as to ensure that the VDD is stable and remains within a valid operating voltage range before bringing RES to high. "*" Make the length of the wiring, which is connected to the RES pin as short as possible, to avoid noise interference.



Instruction Set Summary

Mnemonic	Description	Instruction Cycle	Flag Affected
Arithmetic	1		
ADD A,[m] ADDM A,[m] ADD A,x ADC A,[m] ADCM A,[m] SUB A,x SUB A,[m] SUBM A,[m] SBC A,[m] SBCM A,[m] DAA [m]	Add data memory to ACC Add ACC to data memory Add immediate data to ACC Add data memory to ACC with carry Add ACC to data memory with carry Subtract immediate data from ACC Subtract data memory from ACC Subtract data memory from ACC with result in data memory Subtract data memory from ACC with carry Subtract data memory from ACC with carry and result in data memory Decimal adjust ACC for addition with result in data memory	$ \begin{array}{c} 1 \\ 1^{(1)} \\ 1 \\ 1 \\ 1^{(1)} \\ 1 \\ 1^{(1)} \\ 1 \\ 1^{(1)} $	Z,C,AC,OV Z,C,AC,OV Z,C,AC,OV Z,C,AC,OV Z,C,AC,OV Z,C,AC,OV Z,C,AC,OV Z,C,AC,OV Z,C,AC,OV Z,C,AC,OV C
Logic Operati	on		
AND A,[m] OR A,[m] XOR A,[m] ANDM A,[m] ORM A,[m] XORM A,[m] AND A,x OR A,x VOR A,x CPL [m] CPLA [m]	AND data memory to ACC OR data memory to ACC Exclusive-OR data memory to ACC AND ACC to data memory OR ACC to data memory Exclusive-OR ACC to data memory AND immediate data to ACC OR immediate data to ACC Exclusive-OR immediate data to ACC Complement data memory Complement data memory with result in ACC	$ \begin{array}{c} 1\\ 1\\ 1^{(1)}\\ 1^{(1)}\\ 1\\ 1\\ 1\\ 1\\ 1\\ 1\\ 1\\ 1\\ 1\\ 1\\ 1\\ 1 \end{array} $	Z Z Z Z Z Z Z Z Z Z
Increment & D	Decrement		
INCA [m] INC [m] DECA [m] DEC [m]	Increment data memory with result in ACC Increment data memory Decrement data memory with result in ACC Decrement data memory	1 1 ⁽¹⁾ 1 1 ⁽¹⁾	Z Z Z Z
Rotate		•	
RRA [m] RR [m] RRCA [m] RRC [m] RLA [m] RL [m] RLCA [m] RLC [m]	Rotate data memory right with result in ACC Rotate data memory right Rotate data memory right through carry with result in ACC Rotate data memory right through carry Rotate data memory left with result in ACC Rotate data memory left Rotate data memory left Rotate data memory left through carry with result in ACC Rotate data memory left through carry	$ \begin{array}{c} 1 \\ 1^{(1)} \\ 1 \\ 1^{(1)} \\ 1^{(1)} \\ 1 \\ 1^{(1)} \\ 1 \end{array} $	None C C None None C C
Data Move			
MOV A,[m] MOV [m],A MOV A,x	Move data memory to ACC Move ACC to data memory Move immediate data to ACC	1 1 ⁽¹⁾ 1	None None None
Bit Operation		(4)	
CLR [m].i SET [m].i	Clear bit of data memory Set bit of data memory	1 ⁽¹⁾ 1 ⁽¹⁾	None None



Mnemonic	Description	Instruction Cycle	Flag Affected
Branch			
JMP addr	Jump unconditionally	2	None
SZ [m]	Skip if data memory is zero	1 ⁽²⁾	None
SZA [m]	Skip if data memory is zero with data movement to ACC	1 ⁽²⁾	None
SZ [m].i	Skip if bit i of data memory is zero	1 ⁽²⁾	None
SNZ [m].i	Skip if bit i of data memory is not zero	1 ⁽²⁾	None
SIZ [m]	Skip if increment data memory is zero	1 ⁽³⁾	None
SDZ [m]	Skip if decrement data memory is zero	1 ⁽³⁾	None
SIZA [m]	Skip if increment data memory is zero with result in ACC	1 ⁽²⁾	None
SDZA [m]	Skip if decrement data memory is zero with result in ACC	1 ⁽²⁾	None
CALL addr	Subroutine call	2	None
RET	Return from subroutine	2	None
RET A,x	Return from subroutine and load immediate data to ACC	2	None
RETI	Return from interrupt	2	None
Table Read			
TABRDC [m]	Read ROM code (current page) to data memory and TBLH	2 ⁽¹⁾	None
TABRDL [m]	Read ROM code (last page) to data memory and TBLH	2 ⁽¹⁾	None
Miscellaneou	S	·	•
NOP	No operation	1	None
CLR [m]	Clear data memory	1 ⁽¹⁾	None
SET [m]	Set data memory	1 ⁽¹⁾	None
CLR WDT	Clear Watchdog Timer	1	TO,PDF
CLR WDT1	Pre-clear Watchdog Timer	1	TO ⁽⁴⁾ ,PDF ⁽⁴⁾
CLR WDT2	Pre-clear Watchdog Timer	1	TO ⁽⁴⁾ ,PDF ⁽⁴⁾
SWAP [m]	Swap nibbles of data memory	1 ⁽¹⁾	None
SWAPA [m]	Swap nibbles of data memory with result in ACC	1	None
HALT	Enter power down mode	1	TO,PDF

Note: x: Immediate data

m: Data memory address

A: Accumulator

i: 0~7 number of bits

addr: Program memory address

 \checkmark : Flag is affected

-: Flag is not affected

- ⁽¹⁾: If a loading to the PCL register occurs, the execution cycle of instructions will be delayed for one more cycle (four system clocks).
- ⁽²⁾: If a skipping to the next instruction occurs, the execution cycle of instructions will be delayed for one more cycle (four system clocks). Otherwise the original instruction cycle is unchanged.
- (3): (1) and (2)
- ⁽⁴⁾: The flags may be affected by the execution status. If the Watchdog Timer is cleared by executing the CLR WDT1 or CLR WDT2 instruction, the TO and PDF are cleared. Otherwise the TO and PDF flags remain unchanged.



Instruction Definition

ADC A,[m]	Add data	memory a	ind carry to	the accu	mulator				
Description	The contents of the specified data memory, accumulator and the carry flag are added multaneously, leaving the result in the accumulator.								
Operation	$ACC \leftarrow A$	ACC+[m]+0	C						
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
		—	\checkmark	\checkmark	\checkmark	\checkmark			
ADCM A,[m]	Add the a	accumulate	or and carr	y to data r	memory				
Description					lory, accum pecified da				
Operation	[m] ← AC	C+[m]+C							
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
		_	\checkmark	\checkmark	\checkmark	\checkmark			
ADD A,[m]	Add data	memory t	o the accu	mulator					
Description	The conte	-	specified		ory and the	e accum			
Operation	$ACC \leftarrow A$	ACC+[m]							
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
			\checkmark	\checkmark	\checkmark	\checkmark			
ADD A,x	Add imm	ediate data	a to the acc	cumulator					
Description	The conte		accumulat	or and the	specified	lata are			
Operation	$ACC \leftarrow A$	ACC+x							
Affected flag(s)									
	то	PDF	OV	Z	AC	С			
		_	\checkmark	\checkmark	\checkmark	\checkmark			
ADDM A,[m]	Add the a	accumulato	or to the da	ita memor	у				
Description		ents of the the data n		data mem	ory and the	e accum			
Operation	$[m] \leftarrow AC$,C+[m]							
Operation Affected flag(s)	[m] ← AC	,C+[III]							
	[m] ← AC	PDF	OV	Z	AC	С			



AND A,[m]	Logical AND	accumulator with	data mer	nory	
Description		cumulator and th esult is stored in	-		nory perfo
Operation	$ACC \leftarrow ACC$	"AND" [m]			
Affected flag(s)	[
	TO F	PDF OV	Z	AC	С
			\checkmark	—	_
AND A,x	Logical AND	immediate data t	o the accu	umulator	
Description		ccumulator and the scored in the accurate	•	ed data per	form a bi
Operation	$ACC \gets ACC$	"AND" x			
Affected flag(s)					
	TO F	PDF OV	Z	AC	С
	—		\checkmark	—	
ANDM A,[m]	Logical AND	data memory wit	h the accu	imulator	
Description	•	ecified data men esult is stored in	•		ator perfo
Operation	$[m] \leftarrow ACC$ "	AND" [m]			
Affected flag(s)	[
	TO F	PDF OV	Z	AC	С
			\checkmark	—	
CALL addr	Subroutine ca	all			
Description	program cour this onto the	on unconditionally ater increments of stack. The indica uction at this add	nce to obta ated addre	ain the add	ress of the
Operation	Stack ← Prog Program Cou	gram Counter+1 nter ← addr			
Affected flag(s)	то		7	40	0
	ТО	PDF OV	Z	AC	С
CLR [m]	Clear data me	emory			
Description	The contents	of the specified	data mem	ory are cle	ared to 0.
Operation	[m] ← 00H				
Affected flag(s)					
• ()					
	TO F	PDF OV	Z	AC	С

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CLR [m].i Clear bit of data memory
Description The bit i of the specified data memory is cleared to 0.
Operation $[m].i \leftarrow 0$
Affected flag(s)
TO PDF OV Z AC C
CLR WDT Clear Watchdog Timer
Description The WDT is cleared (clears the WDT). The power down bit cleared.
Operation $WDT \leftarrow 00H$ PDF and TO $\leftarrow 0$
Affected flag(s)
TO PDF OV Z AC C
0 0 — — — —
CLR WDT1 Preclear Watchdog Timer
Description Together with CLR WDT2, clears the WDT. PDF and TO a of this instruction without the other preclear instruction just plies this instruction has been executed and the TO and P
Operation $WDT \leftarrow 00H^*$ PDF and TO $\leftarrow 0^*$
Affected flag(s)
TO PDF OV Z AC C 0* 0* — …<
CLR WDT2 Preclear Watchdog Timer
Description Together with CLR WDT1, clears the WDT. PDF and TO a of this instruction without the other preclear instruction, s plies this instruction has been executed and the TO and F
Operation $WDT \leftarrow 00H^*$
PDF and TO $\leftarrow 0^*$
Affected flag(s) PDF and TO \leftarrow 0*
Affected flag(s)
Affected flag(s)
TO PDF OV Z AC C 0* 0* — …<
Affected flag(s) TO PDF OV Z AC C 0* 0* — — — — — CPL [m] Description Each bit of the specified data memory is logically completed
TO PDF OV Z AC C 0* 0* - - - - - CPL [m] Complement data memory Each bit of the specified data memory is logically complex which previously contained a 1 are changed to 0 and vice Complement are changed to 0 and vice
Affected flag(s) TO PDF OV Z AC C 0^* 0^* $ -$ CPL [m] Complement data memory Complement data memory Each bit of the specified data memory is logically complement which previously contained a 1 are changed to 0 and vice Operation $[m] \leftarrow [\overline{m}]$



CPLA [m]	Complement data memory and place result in the accumulator
Description	Each bit of the specified data memory is logically complemented (1's complement). E which previously contained a 1 are changed to 0 and vice-versa. The complemented res is stored in the accumulator and the contents of the data memory remain unchanged.
Operation	$ACC \leftarrow [\overline{m}]$
Affected flag(s)	
	TO PDF OV Z AC C
	/
DAA [m]	Decimal-Adjust accumulator for addition
Description	The accumulator value is adjusted to the BCD (Binary Coded Decimal) code. The accur lator is divided into two nibbles. Each nibble is adjusted to the BCD code and an inter carry (AC1) will be done if the low nibble of the accumulator is greater than 9. The BCD justment is done by adding 6 to the original value if the original value is greater than 9 c carry (AC or C) is set; otherwise the original value remains unchanged. The result is sto in the data memory and only the carry flag (C) may be affected.
Operation	If ACC.3~ACC.0 >9 or AC=1 then [m].3~[m].0 \leftarrow (ACC.3~ACC.0)+6, AC1= \overline{AC} else [m].3~[m].0 \leftarrow (ACC.3~ACC.0), AC1=0 and If ACC.7~ACC.4+AC1 >9 or C=1 then [m].7~[m].4 \leftarrow ACC.7~ACC.4+6+AC1,C=1 else [m].7~[m].4 \leftarrow ACC.7~ACC.4+AC1,C=C
Affected flag(s)	
	TO PDF OV Z AC C
DEC [m]	Decrement data memory
DEC [m] Description	
	Decrement data memory
Description	Decrement data memory Data in the specified data memory is decremented by 1.
Description Operation	Decrement data memory Data in the specified data memory is decremented by 1.
Description Operation	Decrement data memory Data in the specified data memory is decremented by 1. [m] ← [m]–1
Description Operation	Decrement data memory Data in the specified data memory is decremented by 1. $[m] \leftarrow [m]-1$ TO PDF OV Z AC C
Description Operation Affected flag(s)	Decrement data memoryData in the specified data memory is decremented by 1. $[m] \leftarrow [m]-1$ TOPDFOVZACC $$
Description Operation Affected flag(s)	Decrement data memory Data in the specified data memory is decremented by 1. $[m] \leftarrow [m]-1$ TO PDF OV Z AC C
Description Operation Affected flag(s) DECA [m] Description	Decrement data memory Data in the specified data memory is decremented by 1. $[m] \leftarrow [m]-1$ TO PDF OV Z AC C Decrement data memory and place result in the accumulator Data in the specified data memory is decremented by 1, leaving the result in the accumulator tor. The contents of the data memory remain unchanged.
Description Operation Affected flag(s) DECA [m] Description Operation	Decrement data memory Data in the specified data memory is decremented by 1. $[m] \leftarrow [m]-1$ TO PDF OV Z AC C Decrement data memory and place result in the accumulator Data in the specified data memory is decremented by 1, leaving the result in the accumulator tor. The contents of the data memory remain unchanged.



HALT	Enter pov	ver down n	node				
Description	the RAM		ers are reta	ined. The	WDT and	prescaler	system clock. The contents o are cleared. The power dowr
Operation	Program PDF \leftarrow 1 TO \leftarrow 0	Counter ←	- Program	Counter+	1		
Affected flag(s)							7
	ТО	PDF	OV	Z	AC	С	
	0	1	—	—	—	—	
INC [m]	Incremer	it data men	nory				
Description	Data in th	ne specified	d data mer	nory is inc	remented	by 1	
Operation	[m] ← [m]+1					
Affected flag(s)		-					
0()	то	PDF	OV	Z	AC	С]
				\checkmark			
INCA [m] Description	Data in th tor. The c	contents of	l data men	nory is incr	emented b	y 1, leavi	ng the result in the accumula
Operation	ACC ← [m]+1					
Affected flag(s)	TO						7
	то	PDF	OV	Z	AC	С	-
		—	—	\checkmark	—		
JMP addr	Directly j	ump					
Description		ram counte passed to	•		he directly	-specified	address unconditionally, and
Operation	Program	Counter ←	addr				
Affected flag(s)							7
	ТО	PDF	OV	Z	AC	С	_
		_					
MOV A,[m]	Move dat	a memory	to the acc	umulator			
	The seat	ants of the	specified (data mom	orv are cor	pied to the	a accumulator
Description	The cont		specified (
Description Operation	ACC \leftarrow [specified				
			specified (
Operation			OV	Z	AC	С	
Operation	ACC ← [m]			· · ·		



HT46R322/HT46R342

MOV A,x	Move imm	nediate da	ta to the a	ccumulato	r	
Description	The 8-bit	data speci	fied by the	code is lo	aded into	the accur
Operation	$ACC \leftarrow x$					
Affected flag(s)						
	ТО	PDF	OV	Z	AC	С
			—	—	_	_
MOV [m],A	Move the	accumula	tor to data	memory		
Description				or are copi	ed to the	specified (
2000.1910.11	memories			01 01 0 000		opeenieu
Operation	[m] ←ACC	2				
Affected flag(s)						
	ТО	PDF	OV	Z	AC	С
				—	_	_
NOP	No operat	ion				
Description	•		ormed. Ex	ecution co	ntinues w	ith the ne
Operation				Counter+1		
Affected flag(s)	riogrami		riogram	Counter		
/	то	PDF	OV	Z	AC	С
					_	_
OR A,[m]	Logical O	R accumu	lator with o	data memo	ory	
Description				he specifie		
Operation	form a bit				e result is	Stored III
	$ACC \leftarrow A$		[III]			
Affected flag(s)	то	PDF	OV	Z	AC	С
				√		
				v		
OR A,x	Logical O	R immedia	ate data to	the accum	nulator	
Description				he specifie	ed data p	erform a b
	The result	is stored	in the accu	umulator.		
Operation	$ACC \leftarrow A$	CC "OR"	x			
Affected flag(s)	то		0)/	7		0
	ТО	PDF	OV	Z	AC	C
					_	_
ORM A,[m]	Logical O	R data me	mory with	the accum	ulator	
Description	Data in th	ne data m	emory (on	e of the d	lata mem	ories) and
	bitwise loo	gical_OR o	operation.	The result	is stored	in the data
Operation	[m] ←AC0	C "OR" [m]			
Affected flag(s)						
	ТО	PDF	OV	Z	AC	С
		—		\checkmark		_



HT46R322/HT46R342

RET	Return fro	m subrou	tine						
Description	The progr	am counte	er is restor	ed from th	e stack. Tł	nis is a 2			
Operation	Program (Counter ←	Stack						
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
		—	—	—	—				
RET A,x	Return an	d place in	nmediate d	ata in the	accumulat	or			
Description	The program counter is restored from the stack and the accumulator loaded with the s fied 8-bit immediate data.								
Operation	Program		- Stack						
	$ACC \leftarrow x$								
Affected flag(s)	то	PDF	OV	Z	AC	С			
	10	FDF	00	2	AC	0			
				_					
RETI	Return fro	om interrup	ot						
Description					e stack, an I) interrupt				
Operation	Program 0 EMI ← 1	Counter ←	- Stack						
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
			—	—	—				
RL [m]	Rotate da	ta memor	y left						
Description	The conte	nts of the s	specified d	ata memoi	ry are rotat	ed 1 bit le			
Operation	[m].(i+1) ∢ [m].0 ← [r].i:bit i of tl	ne data me	emory (i=0	~6)			
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
		—	—	—	—				
RLA [m]	Rotate da	ta memor	v left and p	lace resul	t in the acc	cumulato			
Description					ted 1 bit lef				
				•	ontents of t				
Operation	ACC.(i+1) ACC.0 ←		m].i:bit i of	the data r	memory (i=	-0~6)			
Affected flag(s)									
	то	PDF	OV	Z	AC	С			
					,	0			



RLC [m]	Rotate da	ta memor	y left throu	gh carry				
Description					ory and the			
Operation	[m].(i+1) ∢ [m].0 ← C C ← [m].	;	n].i:bit i of tl	he data m	emory (i=0	~6)		
Affected flag(s)								
	ТО	PDF	OV	Z	AC	С		
			_		_			
RLCA [m]	Rotate lef	t through	carry and p	place resu	It in the ac	cumulat		
Description	carry bit a	nd the orig	ginal carry	flag is rota	ne carry flag ated into bi ne data me	t 0 positi		
Operation	ACC.(i+1) ACC.0 ← C ← [m].	С	[m].i:bit i of	the data	memory (i=	=0~6)		
Affected flag(s)								
	ТО	PDF	OV	Z	AC	С		
			_		_	\checkmark		
RR [m]	Rotate da	ta memor	y right					
Description	The conte	nts of the	specified d	ata memo	rv are rotat	ed 1 hit		
	The contents of the specified data memory are rotated 1 bit righ $[m]$.i \leftarrow $[m]$.(i+1); $[m]$.i:bit i of the data memory (i=0~6)							
Operation	[m].i ← [n [m].7 ← [r	- · · ·						
Operation Affected flag(s)		- · · ·						
		- · · ·						
	[m].7 ← [r	n].0	n].i:bit i of ti	he data m	emory (i=0	~6)		
	[m].7 ← [r 	n].0 PDF	n].i:bit i of ti	he data m Z	AC	~6)		
Affected flag(s)	[m].7 ← [r TO — Rotate rig Data in th	n].0 PDF — ht and pla e specified	OV OV OV Ince result in d data mer	E data m	AC	C C ight with		
Affected flag(s)	[m].7 ← [r TO — Rotate rig Data in th the rotate	n].0 PDF ht and pla e specified d result in f - [m].(i+1);	OV OV Ince result in d data men the accumu	Le data m Z 	AC AC mulator ated 1 bit r	C C ight with		
Affected flag(s) RRA [m] Description	[m].7 \leftarrow [r TO Rotate rig Data in th the rotate ACC.(i) \leftarrow	n].0 PDF ht and pla e specified d result in f - [m].(i+1);	OV OV Ince result in d data men the accumu	Le data m Z 	AC AC Imulator ated 1 bit r	C C ight with		
Affected flag(s) RRA [m] Description Operation	[m].7 \leftarrow [r TO Rotate rig Data in th the rotate ACC.(i) \leftarrow	n].0 PDF ht and pla e specified d result in f - [m].(i+1);	OV OV Ince result in d data men the accumu	Le data m Z 	AC AC Imulator ated 1 bit r	C C ight with		
Affected flag(s) RRA [m] Description Operation	[m].7 ← [r TO Rotate rig Data in th the rotate ACC.(i) ← ACC.7 ←	n].0 PDF ht and pla e specified d result in - [m].(i+1); [m].0	OV OV Ince result in d data mer the accumu ; [m].i:bit i d	Le data m Z 	AC AC Imulator ated 1 bit r contents of a memory (C C ight with of the da (i=0~6)		
Affected flag(s) RRA [m] Description Operation Affected flag(s)	[m].7 \leftarrow [r TO — Rotate rig Data in th the rotate ACC.(i) \leftarrow ACC.7 \leftarrow TO —	n].0 PDF — ht and pla e specified d result in fresult in [m].0 PDF —	OV OV Ince result in d data mer the accumu ; [m].i:bit i d OV	z n the accu nory is rot ulator. The of the data Z 	AC AC AC AC AC AC AC AC AC	C C ight with of the da (i=0~6)		
Affected flag(s) RRA [m] Description Operation Affected flag(s) RRC [m]	[m].7 ← [r TO TO Rotate rig Data in th the rotate ACC.(i) ← ACC.7 ← TO TO Rotate da	n].0 PDF — ht and pla e specified d result in f - [m].(i+1); [m].0 PDF — ta memor	OV	n the accu nothe accu nory is rot ulator. The of the data Z ugh carry	AC AC AC amulator ated 1 bit r contents of a memory of AC AC	C C ight with of the da (i=0~6) C		
Affected flag(s) RRA [m] Description Operation Affected flag(s)	[m].7 ← [r TO TO Rotate rig Data in th the rotate ACC.(i) ← ACC.7 ← TO TO Rotate da The conte	n].0 PDF ht and pla e specified d result in f - [m].(i+1); [m].0 PDF 	OV O	n the accu nory is rot ulator. The of the data Z ugh carry data men	AC AC AC AC AC AC AC AC AC	C C ight with of the da (i=0~6) C C 		
Affected flag(s) RRA [m] Description Operation Affected flag(s) RRC [m]	[m].7 ← [r TO TO Rotate rig Data in th the rotate ACC.(i) ← ACC.7 ← TO TO Rotate da The conte right. Bit 0	n].0 PDF — ht and pla e specified d result in t i (i+1); [m].0 PDF — ta memor ents of the preplaces n].(i+1); [m];	OV OV Ceresult in OV Ceresult in O Ceresult Ceresu	The data m Z The the accur nory is rot ulator. The of the data Z The data men pit; the original	AC AC AC AC AC AC AC AC AC AC AC	C C ight with of the dar (i=0~6) C C C ne carry flag is re		
Affected flag(s) RRA [m] Description Operation Affected flag(s) RRC [m] Description	[m].7 ← [r TO TO Rotate rig Data in th the rotated ACC.(i) ← ACC.7 ← TO TO C Rotate da The conte right. Bit (C [m].i ← [rr [m].7 ← C	n].0 PDF — ht and pla e specified d result in t i (i+1); [m].0 PDF — ta memor ents of the preplaces n].(i+1); [m];	OV OV Ceresult in OV Ceresult in O Ceresult Ceresu	The data m Z The the accur nory is rot ulator. The of the data Z The data men pit; the original	AC AC AC AC AC AC AC AC AC AC AC	C C ight with of the dar (i=0~6) C C C ne carry flag is re		
Affected flag(s) RRA [m] Description Operation Affected flag(s) RRC [m] Description Operation	[m].7 ← [r TO TO Rotate rig Data in th the rotated ACC.(i) ← ACC.7 ← TO TO C Rotate da The conte right. Bit (C [m].i ← [rr [m].7 ← C	n].0 PDF — ht and pla e specified d result in t i (i+1); [m].0 PDF — ta memor ents of the preplaces n].(i+1); [m];	OV OV Ceresult in OV Ceresult in O Ceresult Ceresu	The data m Z The the accur nory is rot ulator. The of the data Z The data men pit; the original	AC AC AC AC AC AC AC AC AC AC AC	C C ight with of the dar (i=0~6) C C C ne carry flag is re		



RRCA [m]	Rotate rig	ght through	carry and	place res	ult in the a	ccumula			
Description	the carry	bit and the	d data men original ca ulator. The	rry flag is	rotated into	o the bit 7			
Operation	ACC.i \leftarrow [m].(i+1); [m].i:bit i of the data memory (i=0~6) ACC.7 \leftarrow C C \leftarrow [m].0								
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
		_	—	—	—				
SBC A,[m]	Subtract	data memo	ory and car	rry from th	e accumul	ator			
Description		Subtract data memory and carry from the accumulator The contents of the specified data memory and the complement of the carry flag are tracted from the accumulator, leaving the result in the accumulator.							
Operation	$ACC \leftarrow A$.CC+[m]+0)						
Affected flag(s)									
	ТО	PDF	OV	Z	AC	C			
					V				
SBCM A,[m]	Subtract	data memo	ory and car	rry from th	e accumul	ator			
Description			specified c cumulator,		5	•			
Operation	$[m] \leftarrow AC$	C+[m]+C							
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
		_							
SDZ [m]	Skip if de	crement d	ata memor	y is 0					
Description	instructio instructio	n is skippe n executior	specified d d. If the res n, is discare erwise proc	sult is 0, th ded and a	e following dummy cy) instructi cle is repl			
Operation	Skip if ([n	n]–1)=0, [m	n] ← ([m]–´	1)					
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
		_	—						
SDZA [m]	Decreme	nt data me	mory and	place resu	It in ACC,	skin if ()			
				•					
Description	instructio unchange executior	n is skippe ed. If the re 1, is discare	specified d d. The resu sult is 0, the ded and a o oceed with	ata memo Ilt is storeo e following dummy cy	d in the acc g instruction cle is repla	emented umulator n, fetcheo iced to g			
Description	instructio unchange executior cles). Oth	n is skippe ed. If the re n, is discard nerwise pro	d. The resu sult is 0, the ded and a c	ata memo Ilt is stored e following dummy cy the next in	d in the acc g instruction cle is repla	emented umulator n, fetcheo iced to g			
·	instructio unchange executior cles). Oth	n is skippe ed. If the re n, is discard nerwise pro	d. The resu sult is 0, the ded and a o oceed with	ata memo Ilt is stored e following dummy cy the next in	d in the acc g instruction cle is repla	emented umulator n, fetcheo iced to g			
Operation	instructio unchange executior cles). Oth	n is skippe ed. If the re n, is discard nerwise pro	d. The resu sult is 0, the ded and a o oceed with	ata memo Ilt is stored e following dummy cy the next in	d in the acc g instruction cle is repla	emented umulator n, fetcheo iced to g			



SET [m]	Set data r	memory							
Description	Each bit of the specified data memory is set to 1.								
Operation	[m] ← FFH								
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
	_	_				_			
]		
SET [m]. i	Set bit of data memory								
Description	Bit i of the	e specified	data mem	nory is set	to 1.				
Operation	[m].i ← 1								
Affected flag(s)							-		
	ТО	PDF	OV	Z	AC	С			
	_					_			
		1	I	1	1	1	1		
SIZ [m]	Skip if inc	rement da	ta memor	y is 0					
Description							by 1. If the result is 0, the for		
	lowing instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (2 cycles). Otherwise proceed with								
	the next instruction (1 cycle).								
Operation	Skip if ([m	n]+1)=0, [m	ר] ← ([m]+	1)					
Affected flag(s)		.,		,					
	ТО	PDF	OV	Z	AC	С			
]		
SIZA [m]	Incremen	t data men	nory and p	lace resul	t in ACC,	skip if 0			
Description	The conte	ents of the	specified d	lata memo	ry are incr	emented b	by 1. If the result is 0, the ne		
	instruction is skipped and the result is stored in the accumulator. The data memory re-								
		-			-		fetched during the current i replaced to get the prop		
							iction (1 cycle).		
Operation	Skip if ([m	n]+1)=0, A	CC ← ([m]	+1)					
Affected flag(s)		- /		. ,					
	ТО	PDF	OV	Z	AC	С			
	_					_			
]		
SNZ [m].i	Skip if bit	i of the da	ta memory	/ is not 0					
Description	If bit i of th	e specified	d data men	nory is not	0, the nex	t instructio	n is skipped. If bit i of the da		
			-			-	current instruction executio		
		ed and a d eed with tł			-	the proper	instruction (2 cycles). Othe		
Operation			IC HOAT INS		cyciej.				
Operation	Skip if [m].I≠U							
Affected flag(s)	TO	DDC	01/	7	40	C]		
	ТО	PDF	OV	Z	AC	C	-		
]		



SUB A,[m]	Subtract of	data memo	ory from the	e accumu	lator				
Description	The specified data memory is subtracted from the contents of the accumulator, leavir result in the accumulator.								
Operation	$ACC \leftarrow ACC + [\overline{m}] + 1$								
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
		—	\checkmark	\checkmark	\checkmark	\checkmark			
SUBM A,[m]	Subtract of	data memo	ory from the	e accumu	lator				
Description	The speci result in th		•	subtracted	l from the c	ontents of	the accumula		
Operation	$[m] \leftarrow AC$	C+[m]+1							
Affected flag(s)									
	ТО	PDF	OV	Z	AC	С			
		—	\checkmark	\checkmark	\checkmark	\checkmark			
SUB A,x	Subtract i	mmediata	data from	the accur	nulator				
Description						ted from t	ne contents o		
Description							ie contents o		
One	tor, leaving the result in the accumulator. ACC \leftarrow ACC+ \bar{x} +1								
Operation	$ACC \leftarrow A$	CC+x+1							
Operation Affected flag(s)	ACC ← A	CC+x+1							
	ACC ← A	CC+x+1 PDF	OV	Z	AC	С			
			OV √	Z √	AC √	С √			
Affected flag(s)	то —	PDF							
Affected flag(s) SWAP [m]	TO — Swap nibl	PDF — bles within	√ the data n	√ nemory	\checkmark	N	amony (1 of t		
Affected flag(s)	TO — Swap nibl	PDF — bles withir	√ the data n high-order i	√ nemory	\checkmark	N	emory (1 of t		
Affected flag(s) SWAP [m]	TO — Swap nibl The low-c	PDF — bles within order and h nterchang	√ the data n nigh-order n ed.	√ nemory	\checkmark	N	emory (1 of t		
Affected flag(s) SWAP [m] Description	TO — Swap nibl The low-c ries) are in	PDF — bles within order and h nterchang	√ the data n nigh-order n ed.	√ nemory	\checkmark	N	emory (1 of t		
Affected flag(s) SWAP [m] Description Operation	TO — Swap nibl The low-c ries) are in	PDF — bles within order and h nterchang	√ the data n nigh-order n ed.	√ nemory	\checkmark	N	emory (1 of t		
Affected flag(s) SWAP [m] Description Operation	TO — Swap nibl The low-o ries) are in [m].3~[m]	PDF — bles within order and h nterchang .0 ↔ [m].7	√ the data n nigh-order n ed. /~[m].4	√ nemory nibbles of	√ the specifi	√ ed data m	emory (1 of t		
Affected flag(s) SWAP [m] Description Operation Affected flag(s)	TO — Swap nibl The low-o ries) are in [m].3~[m] TO —	PDF 	√ the data n nigh-order n ed. '~[m].4 OV 	√ nemory nibbles of Z 	√ the specifi AC —	√ ed data m C —	emory (1 of t		
Affected flag(s) SWAP [m] Description Operation Affected flag(s) SWAPA [m]	TO — Swap nibl The low-o ries) are in [m].3~[m] TO — Swap data	PDF 	√ the data n high-order n ed. '~[m].4 OV and place	√ nemory nibbles of Z result in t	√ the specifi AC — he accumu	√ ed data m C ilator			
Affected flag(s) SWAP [m] Description Affected flag(s) SWAPA [m] Description	TO — Swap nibl The low-o ries) are in [m].3~[m] TO — Swap data The low-o	PDF 	√ the data n high-order n ed. '~[m].4 OV and place high-order n	√ nemory nibbles of Z result in t	√ the specifi AC — he accumu	√ ed data m C ulator ed data me	emory (1 of t mory are inte		
Affected flag(s) SWAP [m] Description Operation Affected flag(s) SWAPA [m]	TO — Swap nibl The low-o ries) are in [m].3~[m] TO — Swap data The low-o	PDF bles within order and h nterchang $.0 \leftrightarrow [m].7$ PDF a memory rder and h sult to the CC.0 \leftarrow [r	√ the data n high-order n ed. '~[m].4 OV and place high-order n accumulat n].7~[m].4	√ nemory nibbles of Z result in t	√ the specifi AC — he accumu	√ ed data m C ulator ed data me	mory are inte		
Affected flag(s) SWAP [m] Description Operation Affected flag(s) SWAPA [m] Description	TO — Swap nibl The low-o ries) are in [m].3~[m] TO — Swap dat The low-o ing the rea ACC.3~A	PDF bles within order and h nterchang $.0 \leftrightarrow [m].7$ PDF a memory rder and h sult to the CC.0 \leftarrow [r	√ the data n high-order n ed. '~[m].4 OV and place high-order n accumulat n].7~[m].4	√ nemory nibbles of Z result in t	√ the specifi AC — he accumu	√ ed data m C ulator ed data me	mory are inte		
Affected flag(s) SWAP [m] Description Operation Affected flag(s) SWAPA [m] Description Operation	TO — Swap nibl The low-o ries) are in [m].3~[m] TO — Swap dat The low-o ing the rea ACC.3~A	PDF bles within order and h nterchang $.0 \leftrightarrow [m].7$ PDF a memory rder and h sult to the CC.0 \leftarrow [r	√ the data n high-order n ed. '~[m].4 OV and place high-order n accumulat n].7~[m].4	√ nemory nibbles of Z result in t	√ the specifi AC — he accumu	√ ed data m C ulator ed data me	mory are inte		



SZ [m]	Skip if da	ta memory	is 0						
Description	If the contents of the specified data memory are 0, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (2 cycles). Otherwise proceed with the next instruction (1 cycle).								
Operation	Skip if [m]=0								
Affected flag(s)	-								
	то	PDF	OV	Z	AC	С			
	_	_		_	_				
SZA [m]	Move dat	a memory	to ACC, s	kip if 0					
Description	The contents of the specified data memory are copied to the accumulator. If the contents is 0, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruction (2 cycles). Otherwise proceed with the next instruction (1 cycle).								
Operation	Skip if [m]=0							
Affected flag(s)							1		
	ТО	PDF	OV	Z	AC	С	-		
						—			
SZ [m].i	Skip if bit	i of the da	ta memor	y is 0					
Description	Skip if bit i of the data memory is 0 If bit i of the specified data memory is 0, the following instruction, fetched during the current instruction execution, is discarded and a dummy cycle is replaced to get the proper instruc- tion (2 cycles). Otherwise proceed with the next instruction (1 cycle).								
Operation	Skip if [m].i=0							
Affected flag(s)							~		
	то	PDF	OV	Z	AC	С	_		
					_				
TABRDC [m]	Move the	ROM code	e (current	page) to T	BLH and o	data mem	ory		
Description		•			,	•	able pointer (TBLP) is moved to TBLH directly.		
Operation		DM code (lo ROM code	• •	e)					
Affected flag(s)							_		
	то	PDF	OV	Z	AC	С	_		
		_	—	_	—	—			
TABRDL [m]	Move the	ROM code	e (last pag	je) to TBLI	H and data	memory			
Description		oyte of ROM memory an		,		•	e pointer (TBLP) is moved to ctly.		
Operation		DM code (lo ROM code	• /	e)					
Affected flag(s)							1		
	ТО	PDF	OV	Z	AC	С	-		



HT46R322/HT46R342

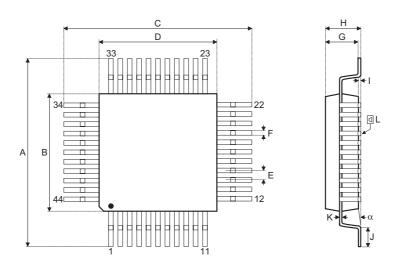
XOR A,[m]	Logical X	OR accum	ulator with	ı data mer	nory			
Description	Data in the accumulator and the indicated data memory perform a bitwise logical sive_OR operation and the result is stored in the accumulator.							
Operation	ACC ← ACC ″XOR″ [m]							
Affected flag(s)								
	ТО	PDF	OV	Z	AC	С		
			—	\checkmark	—	_		
XORM A,[m]	Logical X	OR data n	nemory wit	h the accu	ımulator			
Description			d data me The result					
Operation	$[m] \leftarrow AC$	C "XOR"	[m]					
Affected flag(s)								
	ТО	PDF	OV	Z	AC	С		
	_		_	\checkmark	_	_		
XOR A,x	Logical X	OR immed	liate data t	the accu	umulator			
Description			ator and th s stored in	•	•			
Operation	$ACC \leftarrow A$	CC "XOR	″ x					
Affected flag(s)								
	то	PDF	OV	Z	AC	С		

 $\sqrt{}$



Package Information

44-pin QFP (10×10) Outline Dimensions



Symbol	Dimensions in mm							
Symbol	Min.	Nom.	Max.					
A	13		13.4					
В	9.9		10.1					
С	13		13.4					
D	9.9		10.1					
E	_	0.8	_					
F	_	0.3	_					
G	1.9		2.2					
Н	_		2.7					
I	0.25		0.5					
J	0.73		0.93					
К	0.1	_	0.2					
L	_	0.1	—					
α	0°		7 °					



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